

AMENDMENTS TO THE CLAIMS

Please amend the claims as follows:

1. (currently amended) A process for coating a substrate, ~~wherein~~ comprising:  
applying a suspension of crystalline oxide particles in a suspending medium having a mean particle size from 0.5 to 9.9 nm ~~is applied~~ to a substrate to form a coating,  
evaporating the suspending medium ~~is evaporated~~ and  
sintering said the coating on the substrate ~~is sintered~~.
2. (currently amended) A process for coating a substrate as claimed in claim 1, wherein oxide particles having a mean particle size of from ~~0.5 to 9.9~~ 0.6 to 9 nm are used.
3. (previously presented) A process for coating a substrate as claimed in claim 1, wherein the oxide particles are BaTiO<sub>3</sub>, SrTiO<sub>3</sub>, Ba<sub>x</sub>Sr<sub>1-x</sub>TiO<sub>3</sub> where x=0.01 to 0.99, Pb(Zr<sub>x</sub>Ti<sub>1-x</sub>)O<sub>3</sub> where x=0.01 to 0.99, Bi<sub>4-x</sub>La<sub>x</sub>Ti<sub>3</sub>O<sub>12</sub> where x=0 to 4 or SrBi<sub>2</sub>Ta<sub>2</sub>O<sub>9</sub>.
4. (previously presented) A process for coating a substrate as claimed in claim 1, wherein the suspending medium is an alcohol or a glycol ether.
5. (new) The process of claim 1, wherein said applying is by a process selected from the group consisting of spraying on or by spin-on.
6. (new) The process of claim 1, wherein said sintering is at a temperature below 1350°C.

7. (new) The process of claim 1, wherein oxide particles having a mean particle size of from 1 to 8 nm are used.

8. (new) The process of claim 1, wherein said substrate is a structured silicon wafer.

9. (new) The process of claim 1, wherein said suspension has a solids content of 1 to 35 wt. %.

10. (new) The process of claim 1, wherein said suspension has a solids content of 5 to 25 wt. %.